

Abstract

Lead-free solder based on an Sn-In-Ag solder alloy, containing between 88 to 98.5 wt.% Sn, between 1 to 10 wt.% In, between 0.5 to 3.5 wt.% Ag, between 0 to 1 wt.% Cu, and a doping with a crystallization modifier, particularly a maximum of 100 ppm neodymium.